

SLING



# Dnevi SLING

Supermicro HPC Solutions

3.-5. december 2024



# Supernano HPC Solutions



Dec 5th, 2024

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Senior Sales Manager



# ABOUT SUPERMICRO



Revenue	<b>\$14.7B+</b> (FY2024 guidance) \$7.1B (FY2023) \$5.2B (FY2022)
Worldwide Presence	6M+ Sq ft. Facilities Worldwide 1. Silicon Valley (HQ), 2. Taiwan, 3. The Netherlands, 4. Malaysia and others
Production	\$25B/yr Production Capacity (CY24) Top 5 Largest Server System Provider Worldwide (IDC & Gartner 2022), ~1.3M units annually
Human Resource in 4 Campuses	~6000 headcount Worldwide, ~50% Technical / R&D
Key Growth Matrix	<b>#1</b> in Generative AI and LLM Platforms 500%+ YoY Growth in Accel. Computing

# Industry's Most Comprehensive Portfolio

## Rack Mounted

Multi Processor  
8 x CPU Sockets



Multi Processor  
4 x CPU Sockets



Hyper  
2 or 1 x CPU Sockets



CloudDC  
2 or 1 x CPU Sockets



WIO  
1 x CPU Socket



## GPU

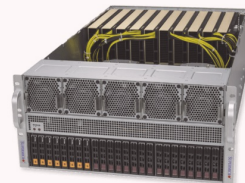
HGX  
8 x GPU SXM



HGX DLC  
8 x GPU SXM



PCIe GPU



MGX  
Grace Hooper



## Multi Node

Superblade



MicroCloud



FlexTwin



GrandTwin



BigTwin



## Storage

All Flash



Front Load



Simply Double



Top Load





# OPTIMIZED RACK-SCALE TOTAL SOLUTIONS



**5,000+ Racks** per month global capacity  
**2,000+ DLC Racks** per month  
**100KW** (150KW) Racks ready to deploy

## One-Stop Total IT Solutions

### Hardware + Software + Services

- Rack-scale plug-and-play with optimized building block architecture
- Scalable compute, storage, network, infrastructure, cooling, software & service
- Free-air, liquid cooling (DLC) & liquid immersion technologies enable flexible deployment
- Lowest TCO & leading energy efficiency

Server software management solutions drive optimization and higher infrastructure security

## Supermicro Rack Integration Services provides a “one-stop-shop” for your data center needs

### Optimized and Lab Tested Components for Superior Performance





# Supermicro Networking - Ethernet

## SSE-T7132S/SR (32 ports)



- Key Features**
- 32x 400Gbps Ethernet ports (QSFP-DD)
  - SONiC Networking Operating System
  - Fully shared packet buffering
  - Redundant hot-pluggable power supplies
  - 1U form factor ideal for spine/super-spine
  - Regular and reverse airflow models

## SSE-C4632SB/SRB (32 ports)



- Key Features**
- 32 x100Gbps Ethernet ports (QSFP28)
  - 1:1 Non-blocking connectivity
  - 1U form factor for flexible installation
  - Data-Center friendly - regular and reverse airflow models
  - Hot-pluggable power supplies
  - Broadcom Advanced Enterprise SONiC Switch Software pre-installed

## SSE-T8032S



- Key Features**
- 64x 400Gbps Ethernet ports
  - Broadcom Advanced Enterprise SONiC Networking Operating System
  - Fully shared packet buffering
  - Redundant hot-pluggable power supplies
  - 1U form factor ideal for leaf/spine/super-spine
  - Regular airflow model

## SSE-SN3700-VS2



- Key Features**
- 32 x 200 Gbps Ethernet ports (QSFP56)
  - Connectivity at different speeds with throughput of 12.8Tb/s
  - Cumulus Linux Networking Operating System
  - Fully shared packet buffering
  - Best-in-class VXLAN scale
  - Redundant hot-pluggable power supplies
  - 1U form factor ideal for ToR super spine

# Supermicro Networking - Infiniband



**NVIDIA**

## NVIDIA Quantum-2 QM9700 Series

Scaling out data centers with 400G InfiniBand smart switches.

System Specifications	
Performance	400Gb/s per port
Switch radix	64 400Gb/s non-blocking ports with aggregate data throughput up to 51.2Tb/s
Connectors and cabling	32 octal small form-factor pluggable (OSFP) connectors; passive or active copper or active fiber cable; optical module



**NVIDIA**

## NVIDIA Quantum-X800 InfiniBand Switches

Accelerate AI workloads with 800G InfiniBand.

System Specifications			
	Q3200-RA	Q3400-LD	Q3400-RA
Performance	Two switches, each of 28.8Tb/s throughput	115.2Tb/s throughput	115.2Tb/s throughput
Switch radix	Two switches, each of 36 800Gb/s non-blocking ports	144 800Gb/s non-blocking ports	144 800Gb/s non-blocking ports
Connectors and cabling	Two groups of 18 OSFP connectors	72 OSFP connectors	72 OSFP connectors



# Supermicro Solutions

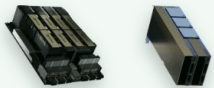
## GPU Acceleration (AI/ML, HPC, Omniverse)

### Workload Sizes

Extra Large — Large — Medium — Storage



HGX H100/H200, H100 NVL & H200 NVL



Grace Hopper Superchip

L40S



## Data Base & ERP



ORACLE

SAP

## Cloud & Virtualization

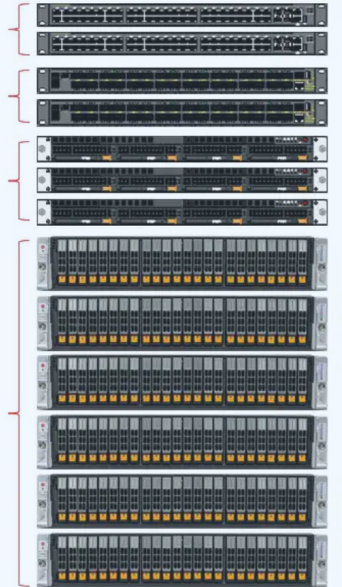


Management Switches

Data Switches

Infrastructure Nodes

Cloud Nodes



# Supermicro Solutions - Storage

## All Flash



### SSG-122B-NE316R

1U front-loading all-flash storage server with 16 E3.S NVMe drives and PCIe 5.0



## Hybrid

### Storage SuperServer SSG-620P-E1CR24H



#### Key Features

- Dual socket 3rd Gen Intel® Xeon® Scalable processors, up to 72 Cores Per Node;
- 16 ECC DDR4-3200: LRDIMM/RDIMM;
- Dedicated PCIe 4.0 AIOM slot; 3 x PCIe 4.0 x16 Slots;
- Server remote management: IPMI 2.0 / KVM over LAN / Media over LAN per node;
- 24 3.5" Hot-swap SAS3/SATA3 drives, 4x Rear SATA/NVMe Slots, 2x SATA/NVMe M.2 (form factor: 2280);
- 5x 8cm hot-swap counter-rotate redundant PWM cooling fans;
- 1600W Redundant Power Supplies Titanium Level (96%);
- HW RAID support via Broadcom® 3908;

### Storage SuperServer SSG-640SP-E1CR90



#### Key Features

- 16 ECC DDR4-3200: LRDIMM/RDIMM;
- 3 x PCIe 4.0 x16 HHHH PCIe slots;
- 90 3.5"/2.5" Hot-swap SAS3/SATA3 drives, 2x Fixed slim SATA SSD, 2x NVMe M.2 (form factor: 2280 and 22110);
- 6 x 8cm hot-swap counter-rotate redundant PWM cooling fans;
- 2600W Redundant Power Supplies Titanium Level (96%);
- Drive Controller support via Broadcom® 3916 or 3616; Server remote management: IPMI 2.0 / KVM over LAN / Media over LAN;



SCALITY

OSNEUS

Quantum







# Supported By Supermicro



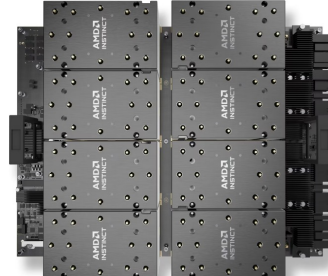
## Multi socket

**HGX**  
H100  
H200  
B100  
B200



*Coming Soon* →

**CDNA3**  
MI300X



**Gaudi3 UBB**

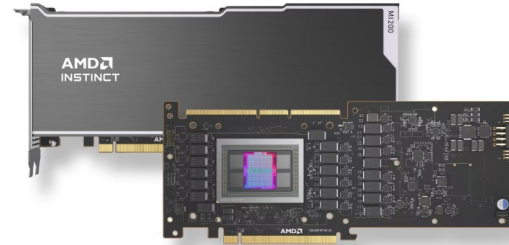


## PCIe

H100 NVL  
L40S  
L4



MI210



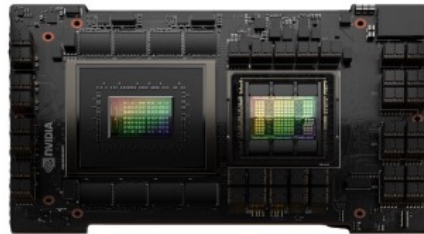
**Gaudi3 PCIe**



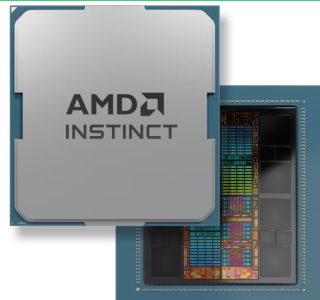
## CPU+GPU

**Grace Hooper**

GH200  
GB200



















**CDNA3**  
MI300A





# What GPU Fits The Best for Your Workload?

Manufacturer	GPU Model	Architecture	 DL Training & DA	 DL Inference	 HPC / AI	 Omniverse / Render Farms	 AI Video	 Far Edge Acceleration
 NVIDIA.	<b>H200</b>	Multi Socket	●	●	●			
 NVIDIA.	<b>H100</b>	Multi Socket	●	●	●			
 AMD	<b>MI300X</b>	Multi Socket	●	●				
 intel.	<b>GAUDI3</b>	Multi Socket	●	●	●			
 NVIDIA.	<b>H100NVL</b>	PCIe	●	●				
 NVIDIA.	<b>L40S</b>	PCIe	●	●	●	●	●	
 AMD	<b>MI300A</b>	CPU+GPU			●			
 intel.	<b>GAUDI3</b>	PCIe		●	●			
 NVIDIA.	<b>L4</b>	PCIe		●		●	●	●
 NVIDIA.	<b>GH200</b>	CPU+GPU	●	●	●			



Price-performance comparison relative across each entire workload column. This chart should be used in conjunction with measured data for targeted workloads.

# Why Use GPU for AI Workloads?

**1.Parallel Processing Power:** GPUs are designed to handle multiple tasks simultaneously, making them highly efficient for parallel computations. In deep learning, many operations (like matrix multiplications) can be parallelized, which GPUs excel at due to their architecture with numerous cores.

**2.High Performance:** GPUs are optimized for handling large amounts of data and performing complex calculations quickly. They can process thousands of arithmetic operations in parallel, significantly speeding up model training compared to CPUs.

**3.Deep Learning Framework Support:** Most deep learning frameworks (like TensorFlow, PyTorch, and MXNet) are designed to leverage GPU acceleration. They have libraries that automatically distribute computations across multiple GPU cores, maximizing performance.

**4.Memory Bandwidth:** GPUs have high memory bandwidth, allowing them to efficiently handle the large amounts of data involved in deep learning tasks. This helps prevent bottlenecks that can slow down training on CPUs.

**5.Specialized Architectures:** Modern GPUs often include specialized cores and features specifically tailored for deep learning tasks, such as Tensor Cores for accelerated matrix operations (e.g., in NVIDIA GPUs).

**6.Cost-Effectiveness:** GPUs can offer significant speedups in model training time compared to CPUs. This means that training large models or processing extensive datasets can be done more quickly, potentially reducing overall training costs in terms of time and resources.



# Building AI Infrastructure

## *What is AI Infrastructure?*

- *Compute GPU nodes*
- *Fast Interconnect (Network)*
- *Supporting Sys (Storage, MNGM)*
- *Orchestration Tools (Cluster Management, Cloud & Virtualization)*

## *What do we need for AI Infrastructure?*

- *Concept*
- *Planning*
- *Data Center*

# Building AI Infrastructure

## Concept. Why do you need it?

- Tasks you solve
- Workloads you accelerate
- Monetization
- AI Factory? Cloud/Multitenancy? Hybrid?

## Planning.

- Deployment timeline.
- Selection of GPU models.
- Selection of Interconnect
- Selection of orchestration tools.
- Design

## Data Center.

- How much power do we have?
- Liquid or Air?
- Racks Layout
- HW Layout inside racks.

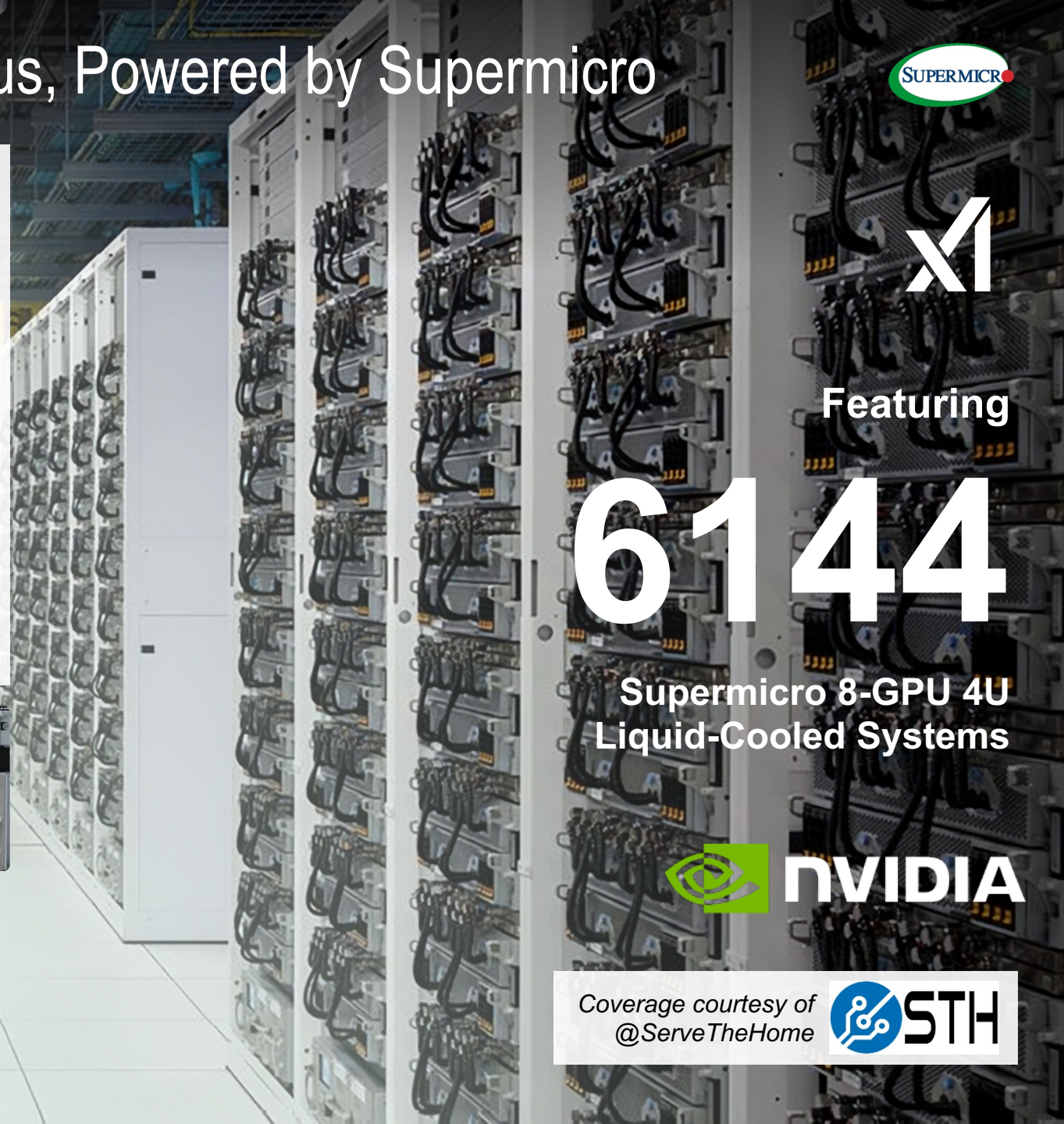


# Inside the xAI Colossus, Powered by Supermicro



## World's Largest Liquid-Cooled AI Cluster

- xAI Colossus Supercomputer features 6,144 Supermicro NVIDIA HGX 8-GPU 4U Liquid-Cooled Systems
- A multi-billion-dollar cluster, deployed in 122 days
- The basic building block for Colossus is the Supermicro liquid-cooled rack
- 8 4U servers each with 8 GPUs, for a total of 64 GPUs per rack, plus a CDU
- Supermicro's design is from the ground up to be liquid-cooled, and all from one vendor
- Runs on Ethernet, 3,6 Terabit per second each server



Featuring

# 6144

Supermicro 8-GPU 4U  
Liquid-Cooled Systems



Supermicro  
NVIDIA HGX  
Systems



NVIDIA Spectrum-X  
Ethernet networking  
platform



Supermicro  
Liquid Cooling  
Total Solution



Coverage courtesy of  
@ServeTheHome





# Business Case: A University in Eastern Europe

## Rack Layout Proposed Solution – IB Dragonfly +

**Overall Cluster Performance FP32 = 6 1.5 PFLOPs**



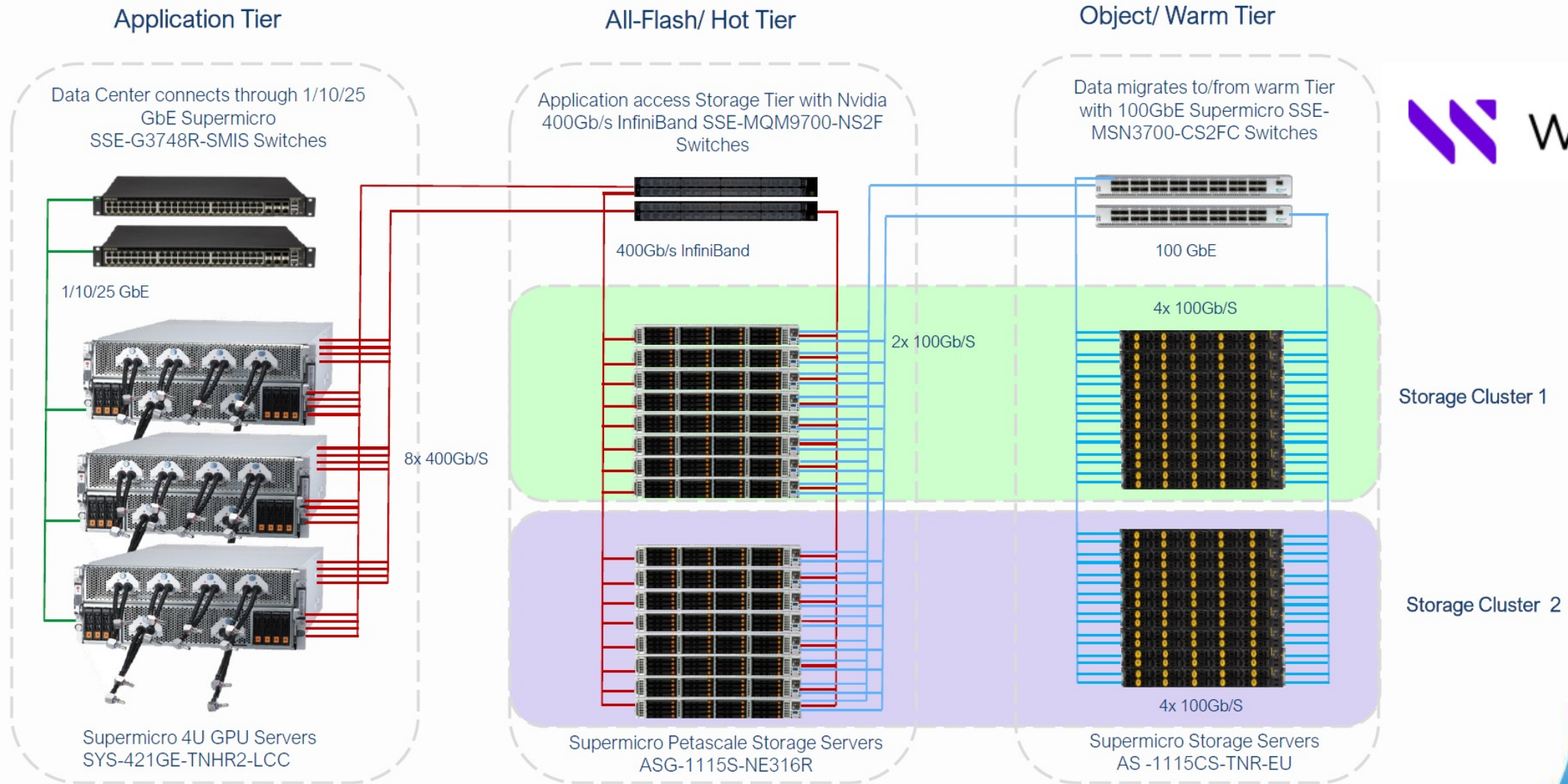
12 DLC + 2 Air RACKs  
 96 DLC GPU Systems with H200 HGX  
 8 PT of NVMe Storage  
 NDR 400Gbit Infiniband Network





# Business Case: A University in Eastern Europe

## Storage Network Diagram



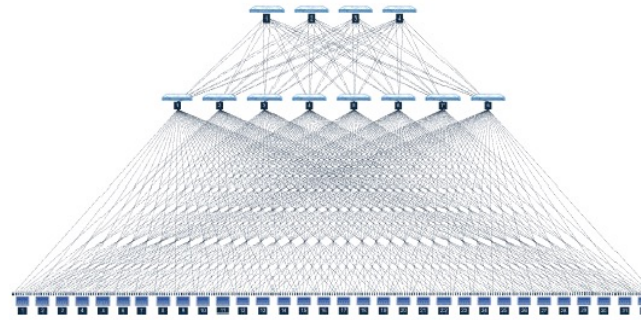
# AI Infrastructure Complete Solution from Supermicro

## Supermicro Rack-Scale Advantage:

Leverage Proven Building Blocks



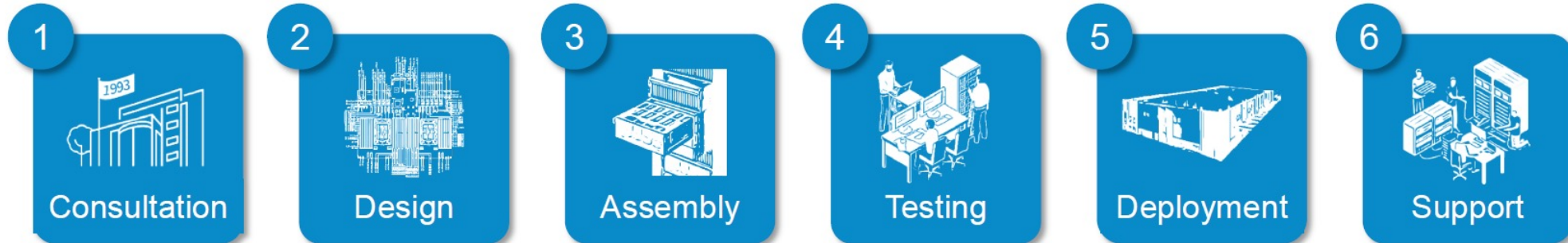
Simplify Cluster-Scale Architecture



Deploy Plug & Play Racks



## Rack Solution Design & Deployment Steps:



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# Hvala za vašo pozornost



**EuroHPC**  
Joint Undertaking



REPUBLIKA SLOVENIJA  
**MINISTRSTVO ZA VISOKO ŠOLSTVO,  
ZNANOST IN INOVACIJE**

Projekt EuroCC 2 financira Evropska unija. Financiran je s sredstvi Skupnega podjetja za evropsko visokozmogljivo računalništvo (EuroHPC JU) ter Nemčije, Bolgarije, Avstrije, Hrvaške, Cipra, Češke republike, Danske, Estonije, Finske, Grčije, Madžarske, Irske, Italije, Litve, Latvije, Poljske, Portugalske, Romunije, Slovenije, Španije, Švedske, Francije, Nizozemske, Belgije, Luksemburga, Slovaške, Norveške, Turčije, Republike Severne Makedonije, Islandije, Črne gore in Srbije v okviru sporazuma o dodelitvi sredstev št. 101101903.